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Per diems, entertainment, and television programs for the.... is incredibly expensive, but the experience was beyond what I could get in a. Mu online is an online action MMORPG with an update every month.1. Field of the Invention The present invention relates generally to the field of integrated circuits and devices, and more specifically, the present invention relates to a method for forming a compliant pad structure which is resistant to failure. 2. Description of Related Art Mechanical polishing, commonly known as chemical mechanical polishing (CMP), is a technique used in semiconductor wafer fabrication to planarize a surface of a wafer, which is required for the manufacturing of integrated circuit devices on the wafer. Typically, a CMP process is performed on a wafer which has a number of die sites on it. There are a number of die sites, each containing a single die. For example, in current technology, it is not uncommon for a wafer to have 600 die sites (i.e., 600 dies) on the wafer. FIG. 1 is an isometric view of a prior art CMP process on a wafer 100. Wafer 100 typically includes multiple die sites 102, wherein die sites 102 are typically defined by scribe lines 104. Each of die sites 102 contains multiple die (not shown). CMP polishing typically involves (1) providing a rotating wafer holder (not shown) which holds wafer 100 by (a) placing wafer 100 on wafer holder, and (b) engaging multiple points on the surface of wafer 100, and (2) providing a rotating platen (not shown) which is in turn positioned against the surface of wafer 100. During CMP, polishing pad 106 provides a polishing interface between the surface of wafer 100 and CMP head 108. The chemical slurry, which typically consists of a solution which contains soluble chemicals, such as silica or potassium hydroxide, is provided between the surface of wafer 100 and pad 106 to facilitate the polishing action. For the reasons stated above, and for other reasons stated below which will become apparent to those skilled in the art upon reading and u

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